

# Temperature-Dependent Microwave Performance of Sb-Heterostructure Backward Diodes for Millimeter-Wave Detection

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Direct detection using unbiased Sb-heterostructure backward diodes has been demonstrated with excellent sensitivity and bandwidth through W-band for passive imagers and radiometers [1-3]. We report the first direct experimental investigation of the temperature-dependent millimeter-wave performance of Sb-heterostructure backward diode detectors. The observed temperature-dependent RF performance is consistent with previous dc temperature studies [3,4]. However, the RF performance provides new insight into device operation and allows a physical model of the phenomenon to be obtained.

The device heterostructure [3] and band diagram are shown in Fig. 1. The performance of the diodes was assessed through dc I-V and on-wafer s-parameter measurement from 1 to 110 GHz, as well as direct microwave detection testing from 4K to 333K. The measured and modeled s-parameters for a 4  $\mu\text{m}^2$  device are shown in Fig. 2. The junction capacitance ( $C_j$ ) extracted from the equivalent circuit model decreases from 18 fF at 298K to 11 fF at 77K, consistent with 1 MHz zero-bias capacitance measurements (Fig. 3). The intrinsic cut-off frequency,  $f_c=1/(2\pi C_j R_s)$ , increases 48% from 740 GHz at 298K to 1.1 THz at 77K. I-V measurements indicate that the curvature,  $\gamma = \left(\frac{\partial^2 I}{\partial V^2}\right) / \frac{\partial I}{\partial V}$ , is constant from room temperature (36  $\text{V}^{-1}$ ) down to 150K, below which it rises to 74  $\text{V}^{-1}$  (Fig. 4). The junction resistance,  $R_j = 1/(\partial I/\partial V)$ , depends only weakly on temperature as expected for tunneling, with  $R_j$  changing from 13.9 k $\Omega$  at 298K to 10.2 k $\Omega$  at 4K; thus the temperature dependence of  $\gamma$  arises from an increase in  $\partial^2 I/\partial V^2$ , rather than a decrease in  $\partial I/\partial V$ . Measured voltage sensitivities ( $\beta_v$ ) at 50 GHz (frequency limited by the test fixture) of 3650 V/W and 7190 V/W were obtained at 298K and 8.9K, respectively (Fig. 5). The increased  $\beta_v$  with decreasing temperature is consistent with the expected  $\beta_v=2Z_0\gamma$  dependence. A 1 dB compression point of 18.5  $\mu\text{W}$  and 7.2  $\mu\text{W}$  at 298K and 8.9K, respectively, was measured (Fig. 6).

Analysis based on Poisson-Schrodinger equation solutions are consistent with the measured results; a 30% decrease in  $C_j$  is calculated from 333K to 77K, compared to a 37% decrease in the measured capacitance. The change in  $C_j$  arises from redistribution of the charge carriers due to a combination of the temperature dependence of the band gap and occupation statistics. This charge carrier redistribution favors backward tunneling compared to forward tunneling, resulting in an increasingly nonlinear current-voltage characteristic as the temperature is lowered. These observations suggest that further increases in room-temperature curvature may be obtained through tailoring of the carrier concentration profile within the device, as well as the possibility of further desensitizing the device to ambient temperature.

## Reference:

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- [3] R. G. Meyers et al., *IEEE Electron Device Lett.*, vol. 25, no.1, pp. 4-6, 2004.
- [4] J. N. Schulman et al., *Electronics Lett.*, vol. 38, no. 2, pp. 94-95, 2002.

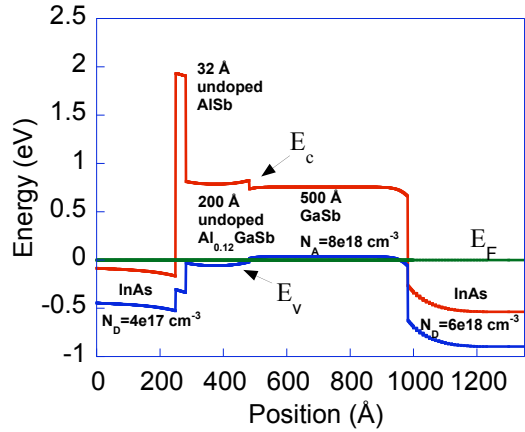


Figure 1: Calculated band diagram for Sb-based heterostructure backward diode.

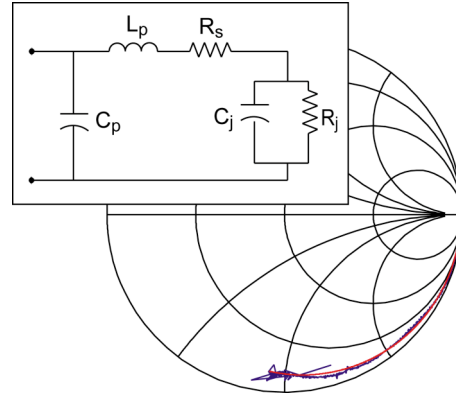


Figure 2: Measured and modeled s-parameters for a  $4 \mu\text{m}^2$  device from 1 to 110 GHz. Inset is the equivalent circuit model used in the modeling.

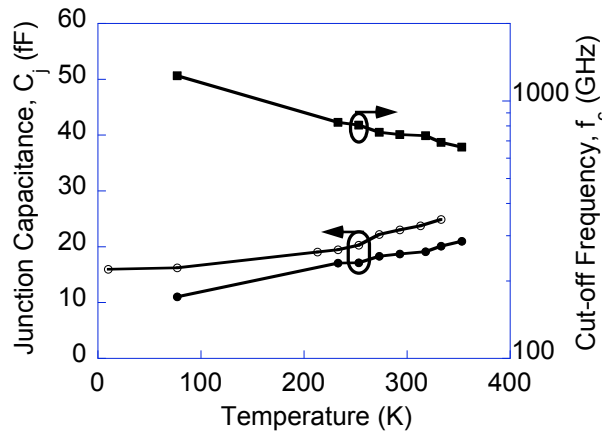


Figure 3: Junction capacitance and calculated cut-off frequency vs. temperature. Data points (●) and (■) represent the extracted  $C_j$  and calculated  $f_c$  based on measured s-parameters. Data points (○) are taken from zero-bias C-V measurement.

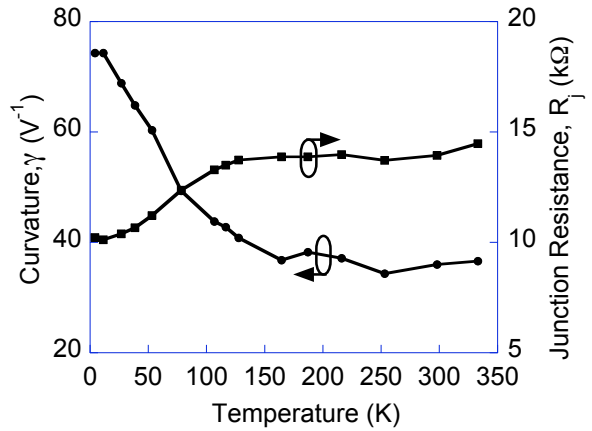


Figure 4: Measured dc curvature ( $\gamma$ ) and junction resistance ( $R_j$ ) vs. temperature.

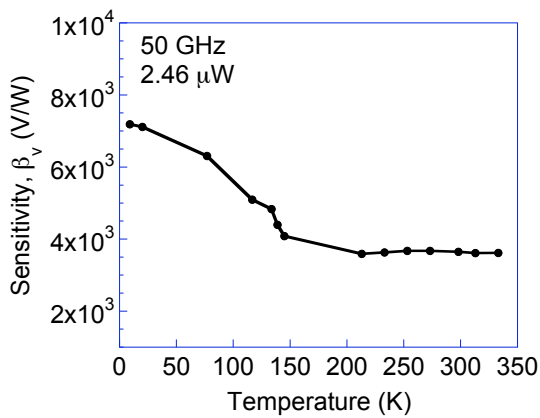


Figure 5: Measured voltage sensitivity vs. temperature at 50 GHz with incident RF power of  $2.46 \mu\text{W}$ .

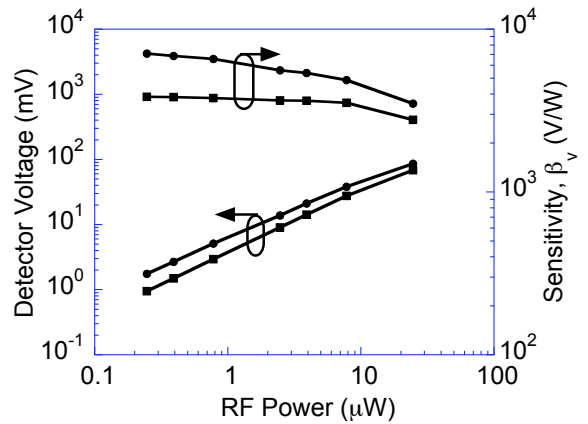


Figure 6: Measured detector voltage and sensitivity vs. incident RF power at 50 GHz. Data points (●) and (■) are taken at 8.9 K and 298 K, respectively.